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**MICROCHIP**

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**PIC24F16KA102 Family  
Data Sheet**

20/28-Pin General Purpose,  
16-Bit Flash Microcontrollers  
with nanoWatt XLP Technology

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# PIC24F16KA102 FAMILY

## 20/28-Pin General Purpose, 16-Bit Flash Microcontrollers with nanoWatt XLP Technology

### Power Management Modes:

- Run – CPU, Flash, SRAM and Peripherals On
- Doze – CPU Clock Runs Slower than Peripherals
- Idle – CPU Off, Flash, SRAM and Peripherals On
- Sleep – CPU, Flash and Peripherals Off and SRAM On
- Deep Sleep – CPU, Flash, SRAM and Most Peripherals Off:
  - Run mode currents down to 8  $\mu$ A typical
  - Idle mode currents down to 2  $\mu$ A typical
  - Deep Sleep mode currents down to 20 nA typical
  - RTCC 490 nA, 32 kHz, 1.8V
  - Watchdog Timer 350 nA, 1.8V typical

### High-Performance CPU:

- Modified Harvard Architecture
- Up to 16 MIPS Operation @ 32 MHz
- 8 MHz Internal Oscillator with 4x PLL Option and Multiple Divide Options
- 17-Bit by 17-Bit Single-Cycle Hardware Multiplier
- 32-Bit by 16-Bit Hardware Divider
- 16-Bit x 16-Bit Working Register Array
- C Compiler Optimized Instruction Set Architecture

### Peripheral Features:

- Hardware Real-Time Clock and Calendar (RTCC):
  - Provides clock, calendar and alarm functions
  - Can run in Deep Sleep Mode
- Programmable Cyclic Redundancy Check (CRC)
- Serial Communication modules:
  - SPI, I<sup>2</sup>C™ and two UART modules
- Three 16-Bit Timers/Counters with Programmable Prescaler
- 16-Bit Capture Inputs
- 16-Bit Compare/PWM Output
- Configurable Open-Drain Outputs on Digital I/O Pins
- Up to Three External Interrupt Sources

### Analog Features:

- 10-Bit, up to 9-Channel Analog-to-Digital Converter:
  - 500 kps conversion rate
  - Conversion available during Sleep and Idle
- Dual Analog Comparators with Programmable Input/Output Configuration
- Charge Time Measurement Unit (CTMU):
  - Used for capacitance sensing
  - Time measurement, down to 1 ns resolution
  - Delay/pulse generation, down to 1 ns resolution

### Special Microcontroller Features:

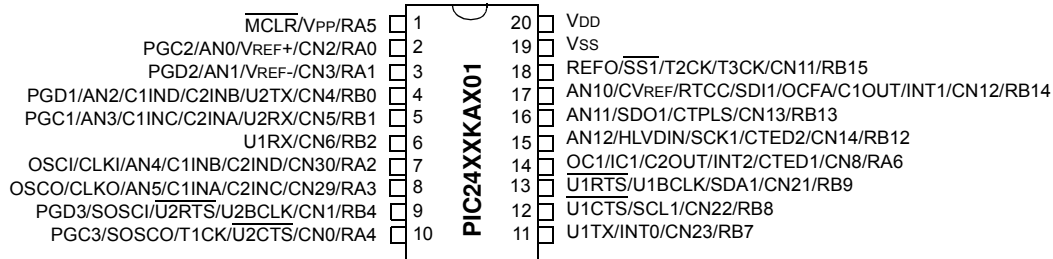
- Operating Voltage Range of 1.8V to 3.6V
- High-Current Sink/Source (18 mA/18 mA) on All I/O Pins
- Flash Program Memory:
  - Erase/write cycles: 10,000 minimum
  - 40-years' data retention minimum
- Data EEPROM:
  - Erase/write cycles: 100,000 minimum
  - 40-years' data retention minimum
- Fail-Safe Clock Monitor
- System Frequency Range Declaration bits:
  - Declaring the frequency range optimizes the current consumption.
- Flexible Watchdog Timer (WDT) with On-Chip, Low-Power RC Oscillator for Reliable Operation
- In-Circuit Serial Programming™ (ICSP™) and In-Circuit Debug (ICD) via two Pins
- Programmable High/Low-Voltage Detect (HLVD)
- Brown-out Reset (BOR):
  - Standard BOR with three programmable trip points; can be disabled in Sleep
- Extreme Low-Power DSBOR for Deep Sleep, LPBOR for all other modes

PIC24F Device	Pins	Program Memory (bytes)	SRAM (bytes)	Data EEPROM (bytes)	Timers 16-Bit	Capture Input	Output Compare/PWM	UART/IrDA®	SPI	I <sup>2</sup> C™	10-Bit A/D (ch)	Comparators	CTMU (ch)	RTCC
08KA101	20	8K	1.5K	512	3	1	1	2	1	1	9	2	9	Y
16KA101	20	16K	1.5K	512	3	1	1	2	1	1	9	2	9	Y
08KA102	28	8K	1.5K	512	3	1	1	2	1	1	9	2	9	Y
16KA102	28	16K	1.5K	512	3	1	1	2	1	1	9	2	9	Y

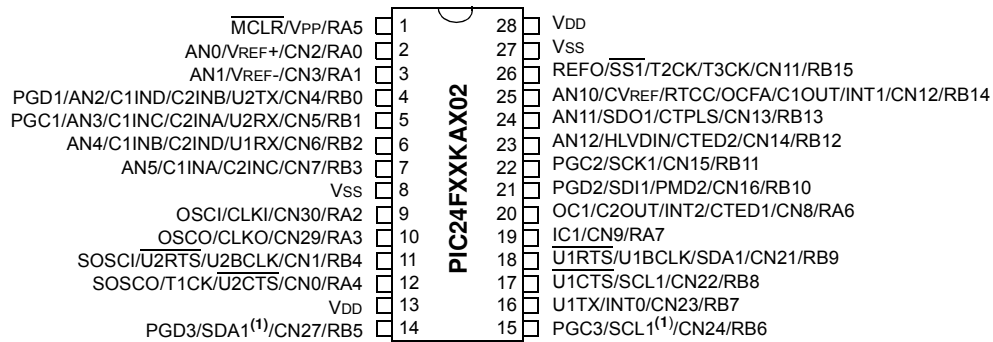
# PIC24F16KA102 FAMILY

## Pin Diagrams

### 20-Pin PDIP, SSOP, SOIC<sup>(2)</sup>



### 28-Pin SPDIP, SSOP, SOIC<sup>(2)</sup>

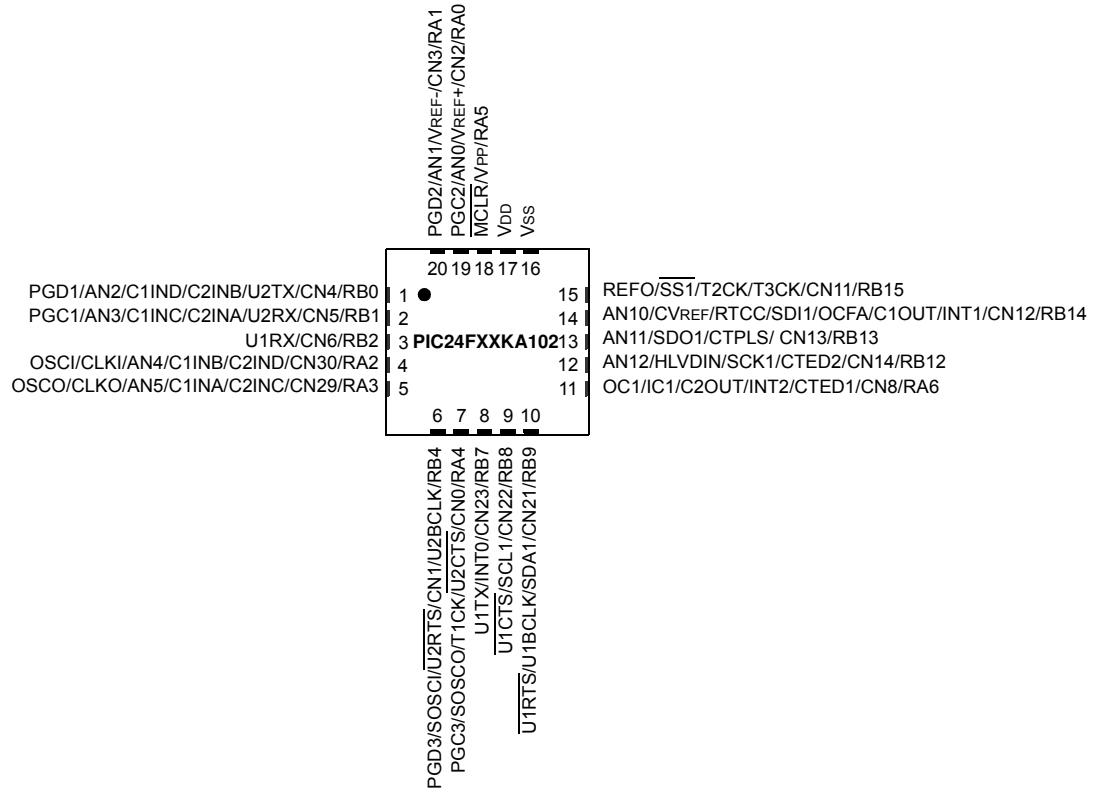


- Note 1:** Alternative multiplexing for SDA1 and SCL1 when the I2CSEL Configuration bit is set.  
**Note 2:** All device pins have a maximum voltage of 3.6V and are not 5V tolerant.

# PIC24F16KA102 FAMILY

## Pin Diagrams (Continued)

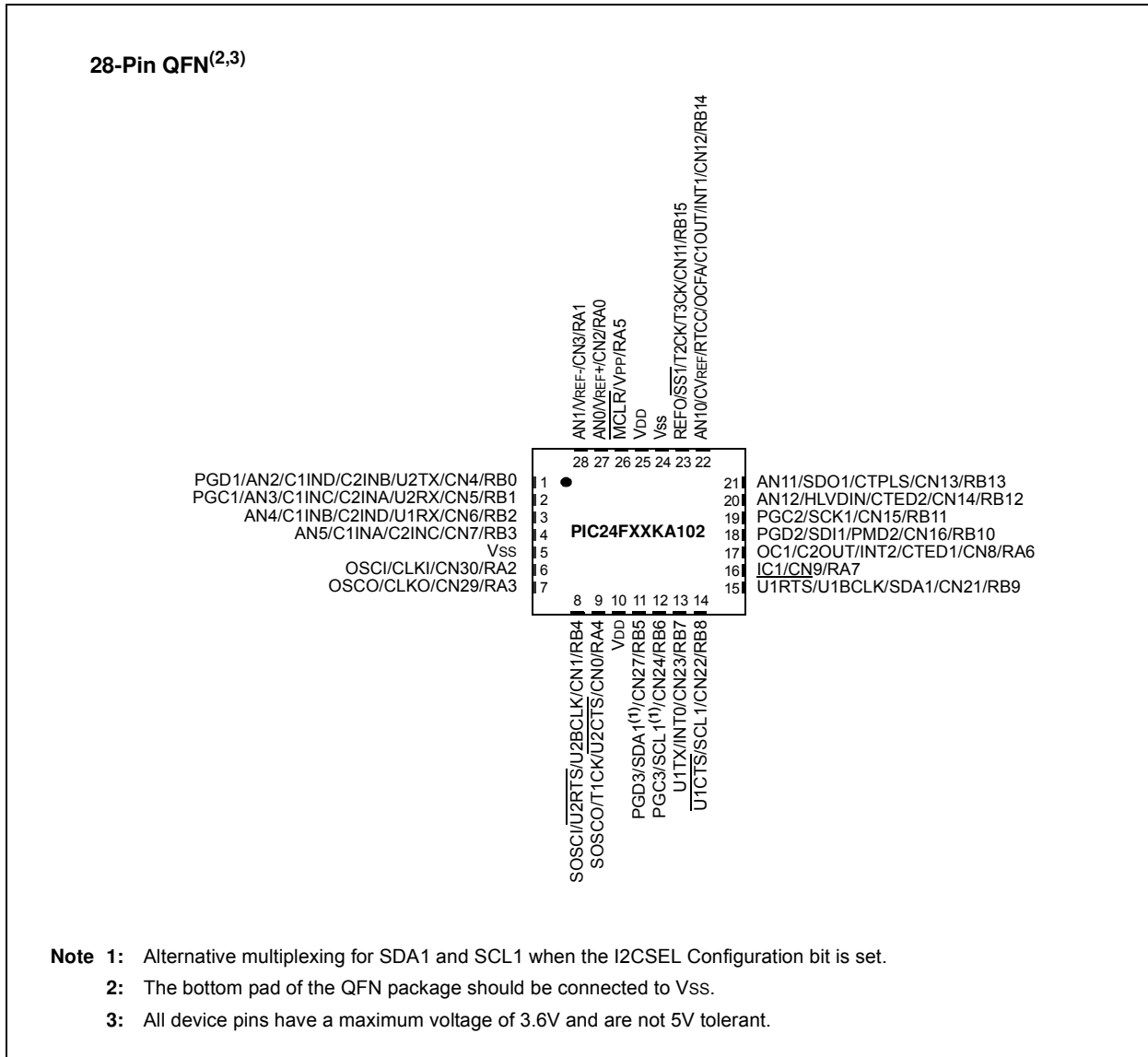
20-Pin QFN<sup>(1,2)</sup>



- Note 1:** The bottom pad of the QFN package should be connected to Vss.
- Note 2:** All device pins have a maximum voltage of 3.6V and are not 5V tolerant.

# PIC24F16KA102 FAMILY

## Pin Diagrams (Continued)



# PIC24F16KA102 FAMILY

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# PIC24F16KA102 FAMILY

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# PIC24F16KA102 FAMILY

## 1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC24F08KA101
- PIC24F16KA101
- PIC24F08KA102
- PIC24F16KA102

The PIC24F16KA102 family introduces a new line of extreme low-power Microchip devices: a 16-bit microcontroller family with a broad peripheral feature set and enhanced computational performance. It also offers a new migration option for those high-performance applications, which may be outgrowing their 8-bit platforms, but do not require the numerical processing power of a digital signal processor.

### 1.1 Core Features

#### 1.1.1 16-BIT ARCHITECTURE

Central to all PIC24F devices is the 16-bit modified Harvard architecture, first introduced with Microchip's dsPIC® digital signal controllers. The PIC24F CPU core offers a wide range of enhancements, such as:

- 16-bit data and 24-bit address paths with the ability to move information between data and memory spaces
- Linear addressing of up to 12 Mbytes (program space) and 64 Kbytes (data)
- A 16-element working register array with built-in software stack support
- A 17 x 17 hardware multiplier with support for integer math
- Hardware support for 32-bit by 16-bit division
- An instruction set that supports multiple addressing modes and is optimized for high-level languages, such as C
- Operational performance up to 16 MIPS

#### 1.1.2 POWER-SAVING TECHNOLOGY

All of the devices in the PIC24F16KA102 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- **On-the-Fly Clock Switching:** The device clock can be changed under software control to the Timer1 source or the internal, low-power RC oscillator during operation, allowing users to incorporate power-saving ideas into their software designs.
- **Doze Mode Operation:** When timing-sensitive applications, such as serial communications, require the uninterrupted operation of peripherals, the CPU clock speed can be selectively reduced, allowing incremental power savings without missing a beat.
- **Instruction-Based Power-Saving Modes:** There are three instruction-based power-saving modes:
  - Idle Mode: The core is shut down while leaving the peripherals active.
  - Sleep Mode: The core and peripherals that require the system clock are shut down, leaving the peripherals that use their own clock, or the clock from other devices, active.
  - Deep Sleep Mode: The core, peripherals (except RTCC and DSWDT), Flash and SRAM are shut down.

#### 1.1.3 OSCILLATOR OPTIONS AND FEATURES

The PIC24F16KA102 family offers five different oscillator options, allowing users a range of choices in developing application hardware. These include:

- Two Crystal modes using crystals or ceramic resonators.
- Two External Clock modes offering the option of a divide-by-2 clock output.
- Two Fast Internal Oscillators (FRCs): One with a nominal 8 MHz output and the other with a nominal 500 kHz output. These outputs can also be divided under software control to provide clock speed as low as 31 kHz or 2 kHz.
- A Phase Locked Loop (PLL) frequency multiplier, available to the External Oscillator modes and the 8 MHz FRC oscillator, which allows clock speeds of up to 32 MHz.
- A separate Internal RC oscillator (LPRC) with a fixed 31 kHz output, which provides a low-power option for timing-insensitive applications.

# PIC24F16KA102 FAMILY

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The internal oscillator block also provides a stable reference source for the Fail-Safe Clock Monitor (FSCM). This option constantly monitors the main clock source against a reference signal provided by the internal oscillator and enables the controller to switch to the internal oscillator, allowing for continued low-speed operation or a safe application shutdown.

## 1.1.4 EASY MIGRATION

Regardless of the memory size, all the devices share the same rich set of peripherals, allowing for a smooth migration path as applications grow and evolve.

The consistent pinout scheme used throughout the entire family also helps in migrating to the next larger device. This is true when moving between devices with the same pin count, or even jumping from 20-pin to 28-pin devices.

The PIC24F family is pin compatible with devices in the dsPIC33 family, and shares some compatibility with the pinout schema for PIC18 and dsPIC30. This extends the ability of applications to grow from the relatively simple, to the powerful and complex.

## 1.2 Other Special Features

- **Communications:** The PIC24F16KA102 family incorporates a range of serial communication peripherals to handle a range of application requirements. There is an I<sup>2</sup>C™ module that supports both the Master and Slave modes of operation. It also comprises UARTs with built-in IrDA® encoders/decoders and an SPI module.
- **Real-Time Clock/Calendar:** This module implements a full-featured clock and calendar with alarm functions in hardware, freeing up timer resources and program memory space for use of the core application.
- **10-Bit A/D Converter:** This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, and faster sampling speed. The 16-deep result buffer can be used either in Sleep to reduce power, or in Active mode to improve throughput.
- **Charge Time Measurement Unit (CTMU)**  
**Interface:** The PIC24F16KA102 family includes the new CTMU interface module, which can be used for capacitive touch sensing, proximity sensing and also for precision time measurement and pulse generation.

## 1.3 Details on Individual Family Members

Devices in the PIC24F16KA102 family are available in 20-pin and 28-pin packages. The general block diagram for all devices is displayed in [Figure 1-1](#).

The devices are different from each other in two ways:

1. Flash program memory (8 Kbytes for PIC24F08KA devices, 16 Kbytes for PIC24F16KA devices).
2. Available I/O pins and ports (18 pins on two ports for 20-pin devices and 24 pins on two ports for 28-pin devices).
3. Alternate SCLx and SDAx pins are available only in 28-pin devices and not in 20-pin devices.

All other features for devices in this family are identical; these are summarized in [Table 1-1](#).

A list of the pin features available on the PIC24F16KA102 family devices, sorted by function, is provided in [Table 1-2](#).

**Note:** [Table 1-1](#) provides the pin location of individual peripheral features and not how they are multiplexed on the same pin. This information is provided in the pinout diagrams on pages [4](#), [5](#) and [6](#) of the data sheet. Multiplexed features are sorted by the priority given to a feature, with the highest priority peripheral being listed first.

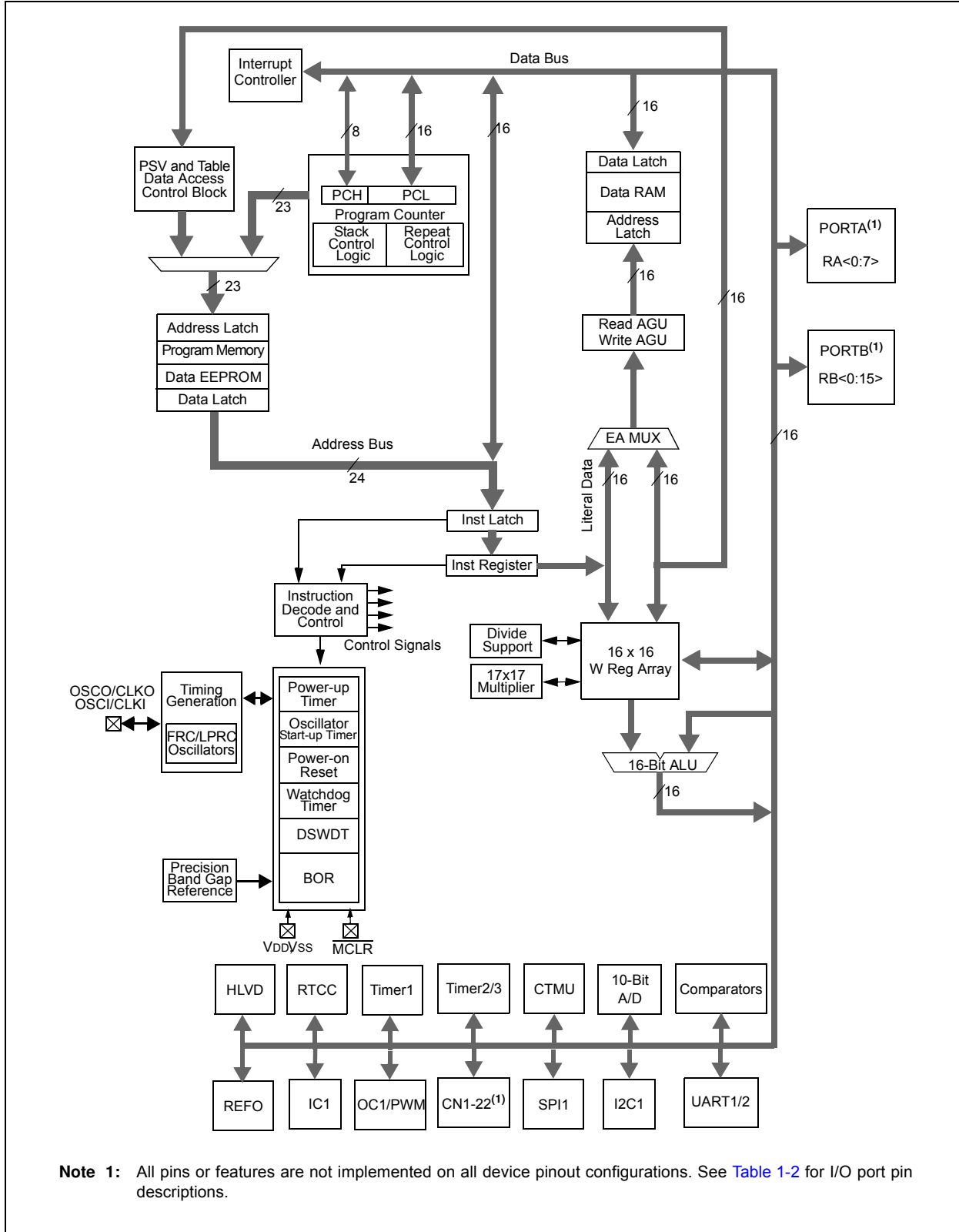
# PIC24F16KA102 FAMILY

**TABLE 1-1: DEVICE FEATURES FOR THE PIC24F16KA102 FAMILY**

Features	PIC24F08KA101	PIC24F16KA101	PIC24F08KA102	PIC24F16KA102
Operating Frequency	DC – 32 MHz			
Program Memory (bytes)	8K	16K	8K	16K
Program Memory (instructions)	2816	5632	2816	5632
Data Memory (bytes)	1536			
Data EEPROM Memory (bytes)	512			
Interrupt Sources (soft vectors/NMI traps)	30 (26/4)			
I/O Ports	PORTA<6:0> PORTB<15:12, 9:7, 4, 2:0>		PORTA<7:0> PORTB<15:0>	
Total I/O Pins	18		24	
Timers: Total Number (16-bit)	3			
32-Bit (from paired 16-bit timers)	1			
Input Capture Channels	1			
Output Compare/PWM Channels	1			
Input Change Notification Interrupt	17		23	
Serial Communications: UART	2			
SPI (3-wire/4-wire)	1			
I <sup>2</sup> C™	1			
10-Bit Analog-to-Digital Module (input channels)	9			
Analog Comparators	2			
Resets (and delays)	POR, BOR, RESET Instruction, $\overline{\text{MCLR}}$ , WDT, Illegal Opcode, REPEAT Instruction, Hardware Traps, Configuration Word Mismatch (PWRT, OST, PLL Lock)			
Instruction Set	76 Base Instructions, Multiple Addressing Mode Variations			
Packages	20-Pin PDIP/SSOP/SOIC/QFN		28-Pin SPDIP/SSOP/SOIC/QFN	

# PIC24F16KA102 FAMILY

FIGURE 1-1: PIC24F16KA102 FAMILY GENERAL BLOCK DIAGRAM



# PIC24F16KA102 FAMILY

**TABLE 1-2: PIC24F16KA102 FAMILY PINOUT DESCRIPTIONS**

Function	Pin Number				I/O	Input Buffer	Description
	20-Pin PDIP/SSOP/SOIC	20-Pin QFN	28-Pin SPDIP/SSOP/SOIC	28-Pin QFN			
AN0	2	19	2	27	I	ANA	A/D Analog Inputs
AN1	3	20	3	28	I	ANA	
AN2	4	1	4	1	I	ANA	
AN3	5	2	5	2	I	ANA	
AN4	7	4	6	3	I	ANA	
AN5	8	5	7	4	I	ANA	
AN10	17	14	25	22	I	ANA	
AN11	16	13	24	21	I	ANA	
AN12	15	12	23	20	I	ANA	
U1BCLK	13	10	18	15	O	—	
U2BCLK	9	6	11	8	O	—	UART2 IrDA Baud Clock
C1INA	8	5	7	4	I	ANA	Comparator 1 Input A (Positive Input)
C1INB	7	4	6	3	I	ANA	Comparator 1 Input B (Negative Input Option 1)
C1INC	5	2	5	2	I	ANA	Comparator Input C (Negative Input Option 2)
C1IND	4	1	4	1	I	ANA	Comparator Input D (Negative Input Option 3)
C1OUT	17	14	25	22	O	—	Comparator 1 Output
C2INA	5	2	5	2	I	ANA	Comparator 2 Input A (Positive Input)
C2INB	4	1	4	1	I	ANA	Comparator 2 Input B (Negative Input Option 1)
C2INC	8	5	7	4	I	ANA	Comparator 2 Input C (Negative Input Option 2)
C2IND	7	4	6	3	I	ANA	Comparator 2 Input D (Negative Input Option 3)
C2OUT	14	11	20	17	O	—	Comparator 2 Output
CLKI	7	4	9	6	I	ANA	Main Clock Input Connection
CLKO	8	5	10	7	O	—	System Clock Output

**Legend:** ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I<sup>2</sup>C™ = I<sup>2</sup>C/SMBus input buffer

**Note 1:** Alternative multiplexing when the I2C1SEL Configuration bit is cleared.

# PIC24F16KA102 FAMILY

**TABLE 1-2: PIC24F16KA102 FAMILY PINOUT DESCRIPTIONS (CONTINUED)**

Function	Pin Number				I/O	Input Buffer	Description	
	20-Pin PDIP/SSOP/SOIC	20-Pin QFN	28-Pin SPDIP/SSOP/SOIC	28-Pin QFN				
CN0	10	7	12	9	I	ST	Interrupt-on-Change Inputs	
CN1	9	6	11	8	I	ST		
CN2	2	19	2	27	I	ST		
CN3	3	20	3	28	I	ST		
CN4	4	1	4	1	I	ST		
CN5	5	2	5	2	I	ST		
CN6	6	3	6	3	I	ST		
CN7	—	—	7	4	I	ST		
CN8	14	11	20	17	I	ST		
CN9	—	—	19	16	I	ST		
CN11	18	15	26	23	I	ST		
CN12	17	14	25	22	I	ST		
CN13	16	13	24	21	I	ST		
CN14	15	12	23	20	I	ST		
CN15	—	—	22	19	I	ST		
CN16	—	—	21	18	I	ST		
CN21	13	10	18	15	I	ST		
CN22	12	9	17	14	I	ST		
CN23	11	8	16	13	I	ST		
CN24	—	—	15	12	I	ST		
CN27	—	—	14	11	I	ST		
CN29	8	5	10	7	I	ST		
CN30	7	4	9	6	I	ST		
CVREF	17	14	25	22	O	ANA		Comparator Voltage Reference Output
CTED1	14	11	20	17	I	ST		CTMU Trigger Edge Input 1
CTED2	15	12	23	20	I	ST		CTMU Trigger Edge Input 2
CTPLS	16	13	24	21	O	—		CTMU Pulse Output
IC1	14	11	19	16	I	ST		Input Capture 1 Input
INT0	11	8	16	13	I	ST		External Interrupt Inputs
INT1	17	14	25	22	I	ST		
INT2	14	11	20	17	I	ST		
HLVDIN	15	12	23	20	I	ANA	HLVD Voltage Input	
MCLR	1	18	1	26	I	ST	Master Clear (device Reset) Input	
OC1	14	11	20	17	O	—	Output Compare/PWM Outputs	
OCFA	17	14	25	22	I	—	Output Compare Fault A	
OSCI	7	4	9	6	I	ANA	Main Oscillator Input Connection	
OSCO	8	5	10	7	O	ANA	Main Oscillator Output Connection	

**Legend:** ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I<sup>2</sup>C™ = I<sup>2</sup>C/SMBus input buffer

**Note 1:** Alternative multiplexing when the I2C1SEL Configuration bit is cleared.

# PIC24F16KA102 FAMILY

**TABLE 1-2: PIC24F16KA102 FAMILY PINOUT DESCRIPTIONS (CONTINUED)**

Function	Pin Number				I/O	Input Buffer	Description
	20-Pin PDIP/SSOP/SOIC	20-Pin QFN	28-Pin SPDIP/SSOP/SOIC	28-Pin QFN			
PGC1	5	2	5	2	I/O	ST	In-Circuit Debugger and ICSP™ Programming Clock
PGD1	4	1	4	1	I/O	ST	In-Circuit Debugger and ICSP Programming Data
PGC2	2	19	22	19	I/O	ST	In-Circuit Debugger and ICSP Programming Clock
PGD2	3	20	21	18	I/O	ST	In-Circuit Debugger and ICSP Programming Data
PGC3	10	7	15	12	I/O	ST	In-Circuit Debugger and ICSP Programming Clock
PGD3	9	6	14	11	I/O	ST	In-Circuit Debugger and ICSP Programming Data
RA0	2	19	2	27	I/O	ST	PORTA Digital I/O
RA1	3	20	3	28	I/O	ST	
RA2	7	4	9	6	I/O	ST	
RA3	8	5	10	7	I/O	ST	
RA4	10	7	12	9	I/O	ST	
RA5	1	18	1	26	I/O	ST	
RA6	14	11	20	17	I/O	ST	
RA7	—	—	19	16	I/O	ST	
RB0	4	1	4	1	I/O	ST	PORTB Digital I/O
RB1	5	2	5	2	I/O	ST	
RB2	6	3	6	3	I/O	ST	
RB3	—	—	7	4	I/O	ST	
RB4	9	6	11	8	I/O	ST	
RB5	—	—	14	11	I/O	ST	
RB6	—	—	15	12	I/O	ST	
RB7	11	8	16	13	I/O	ST	
RB8	12	9	17	14	I/O	ST	
RB9	13	10	18	15	I/O	ST	
RB10	—	—	21	18	I/O	ST	
RB11	—	—	22	19	I/O	ST	
RB12	15	12	23	20	I/O	ST	
RB13	16	13	24	21	I/O	ST	
RB14	17	14	25	22	I/O	ST	
RB15	18	15	26	23	I/O	ST	
REFO	18	15	26	23	O	—	Reference Clock Output
RTCC	17	14	25	22	O	—	Real-Time Clock Alarm Output
SCK1	15	12	22	19	I/O	ST	SPI1 Serial Clock Input/Output
SCL1	12	9	17, 15 <sup>(1)</sup>	14, 12 <sup>(1)</sup>	I/O	I <sup>2</sup> C	I <sup>2</sup> C1 Synchronous Serial Clock Input/Output
SDA1	13	10	18, 14 <sup>(1)</sup>	15, 11 <sup>(1)</sup>	I/O	I <sup>2</sup> C	I <sup>2</sup> C1 Data Input/Output
SDI1	17	14	21	18	I	ST	SPI1 Serial Data Input
SDO1	16	13	24	21	O	—	SPI1 Serial Data Output
SOSCI	9	6	11	8	I	ANA	Secondary Oscillator Input
SOSCO	10	7	12	9	O	ANA	Secondary Oscillator Output
SS1	18	15	26	23	I/O	ST	Slave Select Input/Frame Select Output (SPI1)

**Legend:** ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I<sup>2</sup>C™ = I<sup>2</sup>C/SMBus input buffer

**Note 1:** Alternative multiplexing when the I2C1SEL Configuration bit is cleared.



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**TABLE 1-2: PIC24F16KA102 FAMILY PINOUT DESCRIPTIONS (CONTINUED)**

Function	Pin Number				I/O	Input Buffer	Description
	20-Pin PDIP/SSOP/SOIC	20-Pin QFN	28-Pin SPDIP/SSOP/SOIC	28-Pin QFN			
T1CK	10	7	12	9	I	ST	Timer1 Clock
T2CK	18	15	26	23	I	ST	Timer2 Clock
T3CK	18	15	26	23	I	ST	Timer3 Clock
U1CTS	12	9	17	14	I	ST	UART1 Clear to Send Input
U1RTS	13	10	18	15	O	—	UART1 Request to Send Output
U1RX	6	3	6	3	I	ST	UART1 Receive
U1TX	11	8	16	13	O	—	UART1 Transmit Output
VDD	20	17	13, 28	10, 25	P	—	Positive Supply for Peripheral Digital Logic and I/O Pins
VPP	1	18	1	26	P	—	Programming Mode Entry Voltage
VREF-	3	20	3	28	I	ANA	A/D and Comparator Reference Voltage (low) Input
VREF+	2	19	2	27	I	ANA	A/D and Comparator Reference Voltage (high) Input
VSS	19	16	8, 27	5, 24	P	—	Ground Reference for Logic and I/O Pin

**Legend:** ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I<sup>2</sup>C™ = I<sup>2</sup>C/SMBus input buffer

**Note 1:** Alternative multiplexing when the I2C1SEL Configuration bit is cleared.

# PIC24F16KA102 FAMILY

## 2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT MICROCONTROLLERS

### 2.1 Basic Connection Requirements

Getting started with the PIC24F16KA102 family of 16-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All VDD and VSS pins (see [Section 2.2 “Power Supply Pins”](#))
- All AVDD and AVSS pins, regardless of whether or not the analog device features are used (see [Section 2.2 “Power Supply Pins”](#))
- MCLR pin (see [Section 2.3 “Master Clear \(MCLR\) Pin”](#))
- VCAP pins (see [Section 2.4 “Voltage Regulator Pin \(VCAP\)”](#))

These pins must also be connected if they are being used in the end application:

- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see [Section 2.5 “ICSP Pins”](#))
- OSCI and OSCO pins when an external oscillator source is used (see [Section 2.6 “External Oscillator Pins”](#))

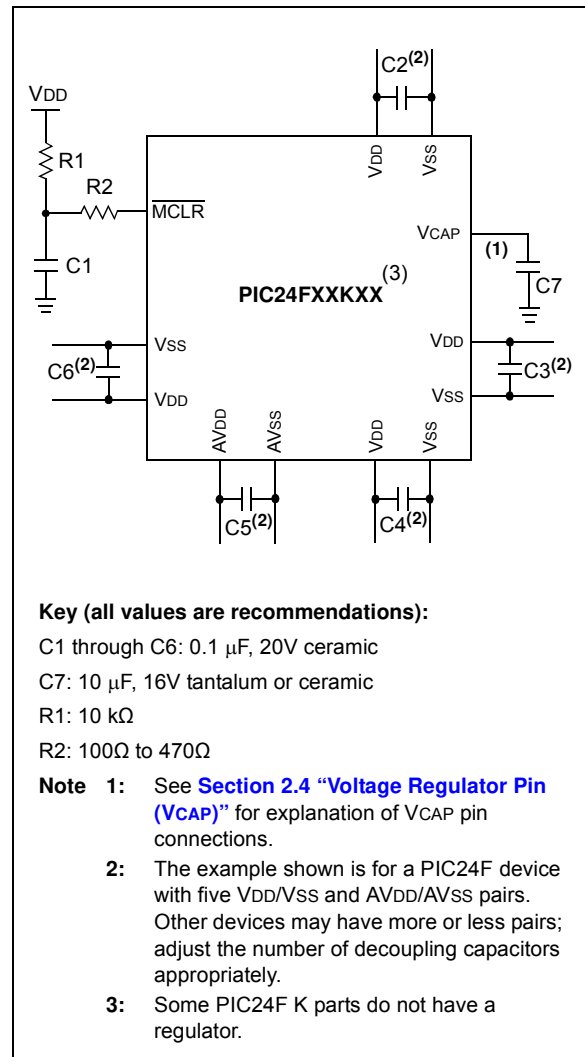
Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

**Note:** The AVDD and AVSS pins must always be connected, regardless of whether any of the analog modules are being used.

The minimum mandatory connections are shown in [Figure 2-1](#).

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



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## 2.2 Power Supply Pins

### 2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1  $\mu\text{F}$  (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01  $\mu\text{F}$  to 0.001  $\mu\text{F}$ . Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1  $\mu\text{F}$  in parallel with 0.001  $\mu\text{F}$ ).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

### 2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7  $\mu\text{F}$  to 47  $\mu\text{F}$ .

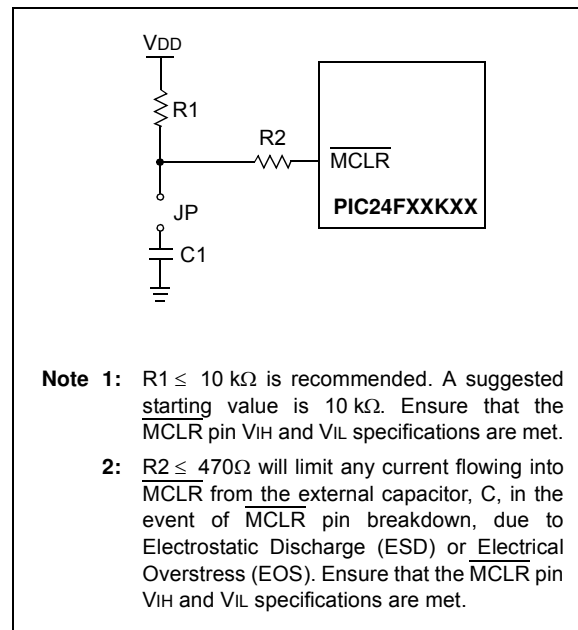
## 2.3 Master Clear ( $\overline{\text{MCLR}}$ ) Pin

The  $\overline{\text{MCLR}}$  pin provides two specific device functions: Device Reset, and Device Programming and Debugging. If programming and debugging are not required in the end application, a direct connection to VDD may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the  $\overline{\text{MCLR}}$  pin. Consequently, specific voltage levels ( $V_{IH}$  and  $V_{IL}$ ) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the  $\overline{\text{MCLR}}$  pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the  $\overline{\text{MCLR}}$  pin should be placed within 0.25 inch (6 mm) of the pin.

**FIGURE 2-2: EXAMPLE OF  $\overline{\text{MCLR}}$  PIN CONNECTIONS**



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## 2.4 Voltage Regulator Pin (VCAP)

**Note:** This section applies only to PIC24F K devices with an on-chip voltage regulator.

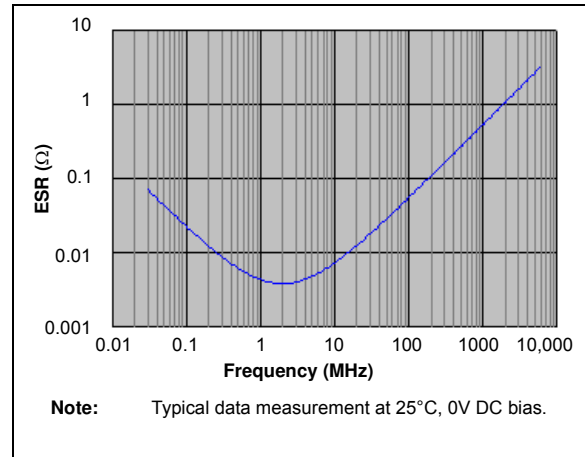
Some of the PIC24F K devices have an internal voltage regulator. These devices have the voltage regulator output brought out on the VCAP pin. On the PIC24F K devices with regulators, a low-ESR ( $< 5\Omega$ ) capacitor is required on the VCAP pin to stabilize the voltage regulator output. The VCAP pin must not be connected to VDD and must use a capacitor of 10  $\mu\text{F}$  connected to ground. The type can be ceramic or tantalum. Suitable examples of capacitors are shown in Table 2-1. Capacitors with equivalent specifications can be used.

Designers may use Figure 2-3 to evaluate ESR equivalence of candidate devices.

The placement of this capacitor should be close to VCAP. It is recommended that the trace length not exceed 0.25 inch (6 mm). Refer to Section 29.0 “Electrical Characteristics” for additional information.

Refer to Section 29.0 “Electrical Characteristics” for information on VDD and VDDCORE.

**FIGURE 2-3: FREQUENCY vs. ESR PERFORMANCE FOR SUGGESTED VCAP**



**TABLE 2-1: SUITABLE CAPACITOR EQUIVALENTS**

Make	Part #	Nominal Capacitance	Base Tolerance	Rated Voltage	Temp. Range
TDK	C3216X7R1C106K	10 $\mu\text{F}$	$\pm 10\%$	16V	-55 to 125°C
TDK	C3216X5R1C106K	10 $\mu\text{F}$	$\pm 10\%$	16V	-55 to 85°C
Panasonic	ECJ-3YX1C106K	10 $\mu\text{F}$	$\pm 10\%$	16V	-55 to 125°C
Panasonic	ECJ-4YB1C106K	10 $\mu\text{F}$	$\pm 10\%$	16V	-55 to 85°C
Murata	GRM32DR71C106KA01L	10 $\mu\text{F}$	$\pm 10\%$	16V	-55 to 125°C
Murata	GRM31CR61C106KC31L	10 $\mu\text{F}$	$\pm 10\%$	16V	-55 to 85°C

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## 2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

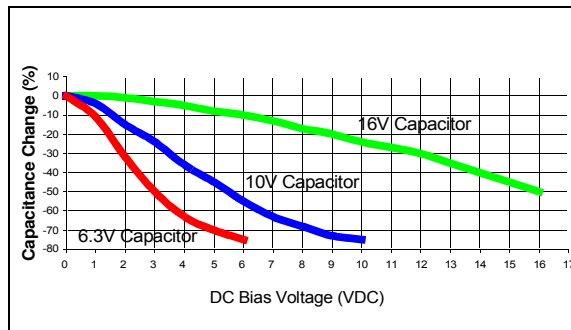
Typical low-cost, 10  $\mu\text{F}$  ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as  $\pm 10\%$  to  $\pm 20\%$  (X5R and X7R), or  $-20\%/+80\%$  (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex:  $\pm 15\%$  over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of  $+22\%/ -82\%$ . Due to the extreme temperature tolerance, a 10  $\mu\text{F}$  nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

A typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in [Figure 2-4](#).

**FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS**



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating, so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at 16V for the 3.3V or 2.5V core voltage. Suggested capacitors are shown in [Table 2-1](#).

## 2.5 ICSP Pins

The PGC and PGD pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100 $\Omega$ .

Pull-up resistors, series diodes and capacitors on the PGC and PGD pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin input voltage high ( $V_{IH}$ ) and input low ( $V_{IL}$ ) requirements.

For device emulation, ensure that the “Communication Channel Select” (i.e., PGCx/PGDx pins), programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to [Section 27.0 “Development Support”](#).

## 2.6 External Oscillator Pins

Many microcontrollers have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to [Section 9.0 “Oscillator Configuration”](#) for details).

The oscillator circuit should be placed on the same side of the board as the device. Place the oscillator circuit close to the respective oscillator pins with no more than 0.5 inch (12 mm) between the circuit components and the pins. The load capacitors should be placed next to the oscillator itself, on the same side of the board.

Use a grounded copper pour around the oscillator circuit to isolate it from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed.

Layout suggestions are shown in [Figure 2-5](#). In-line packages may be handled with a single-sided layout that completely encompasses the oscillator pins. With fine-pitch packages, it is not always possible to completely surround the pins and components. A suitable solution is to tie the broken guard sections to a mirrored ground layer. In all cases, the guard trace(s) must be returned to ground.

In planning the application’s routing and I/O assignments, ensure that adjacent port pins and other signals, in close proximity to the oscillator, are benign (i.e., free of high frequencies, short rise and fall times, and other similar noise).

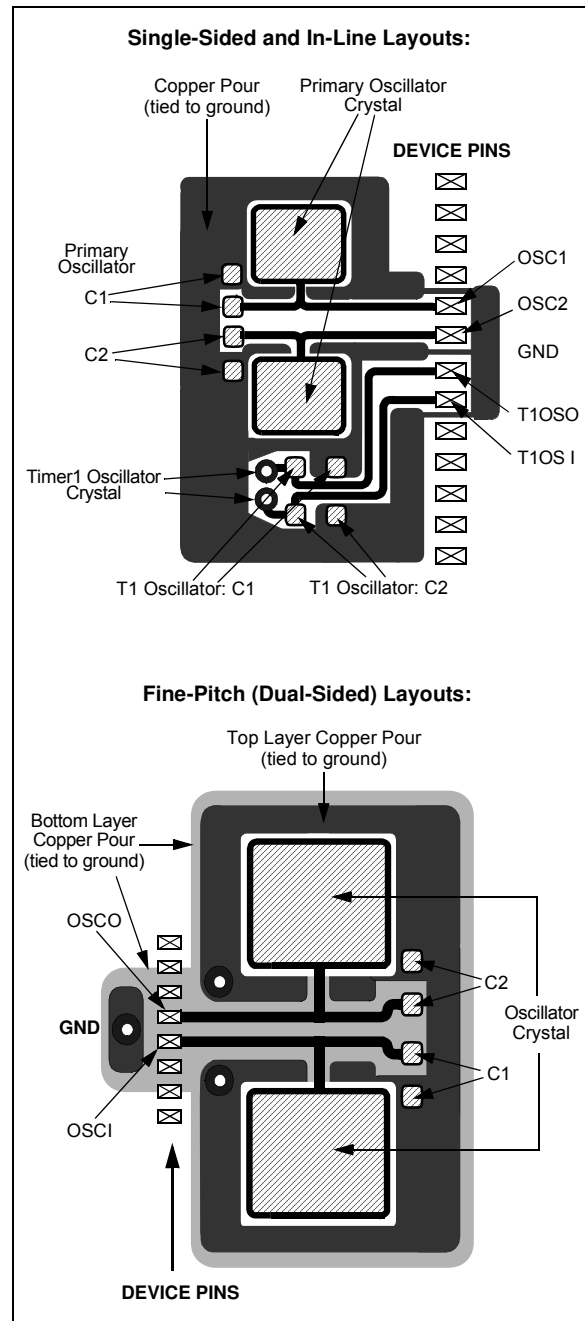
For additional information and design guidance on oscillator circuits, please refer to these Microchip Application Notes, available at the corporate web site ([www.microchip.com](http://www.microchip.com)):

- AN826, “Crystal Oscillator Basics and Crystal Selection for rPIC™ and PICmicro® Devices”
- AN849, “Basic PICmicro® Oscillator Design”
- AN943, “Practical PICmicro® Oscillator Analysis and Design”
- AN949, “Making Your Oscillator Work”

## 2.7 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state. Alternatively, connect a 1 kΩ to 10 kΩ resistor to Vss on unused pins and drive the output to logic low.

**FIGURE 2-5: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT**



# PIC24F16KA102 FAMILY

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NOTES:

## 3.0 CPU

**Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the CPU, refer to the “*PIC24F Family Reference Manual*”, **Section 2. “CPU”** (DS39703).

The PIC24F CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set and a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M instructions of user program memory space. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (MOV.D) instruction and the table instructions. Overhead-free program loop constructs are supported using the REPEAT instructions, which are interruptible at any point.

PIC24F devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16<sup>th</sup> working register (W15) operates as a Software Stack Pointer (SSP) for interrupts and calls.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K word boundary of either program memory or data EEPROM memory defined by the 8-bit Program Space Visibility Page Address (PSVPAG) register. The program to data space mapping feature lets any instruction access program space as if it were data space.

The Instruction Set Architecture (ISA) has been significantly enhanced beyond that of the PIC18, but maintains an acceptable level of backward compatibility. All PIC18 instructions and addressing modes are supported, either directly, or through simple macros. Many of the ISA enhancements have been driven by compiler efficiency needs.

The core supports Inherent (no operand), Relative, Literal, Memory Direct and three groups of addressing modes. All modes support Register Direct and various Register Indirect modes. Each group offers up to seven addressing modes. Instructions are associated with predefined addressing modes depending upon their functional requirements.

For most instructions, the core is capable of executing a data (or program data) memory read, a working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing trinary operations (that is,  $A + B = C$ ) to be executed in a single cycle.

A high-speed, 17-bit by 17-bit multiplier has been included to significantly enhance the core arithmetic capability and throughput. The multiplier supports Signed, Unsigned and Mixed mode, 16-bit by 16-bit or 8-bit by 8-bit integer multiplication. All multiply instructions execute in a single cycle.

The 16-bit ALU has been enhanced with integer divide assist hardware that supports an iterative non-restoring divide algorithm. It operates in conjunction with the REPEAT instruction looping mechanism and a selection of iterative divide instructions to support 32-bit (or 16-bit), divided by 16-bit integer signed and unsigned division. All divide operations require 19 cycles to complete but are interruptible at any cycle boundary.

The PIC24F has a vectored exception scheme with up to eight sources of non-maskable traps and up to 118 interrupt sources. Each interrupt source can be assigned to one of seven priority levels.

A block diagram of the CPU is illustrated in [Figure 3-1](#).

### 3.1 Programmer's Model

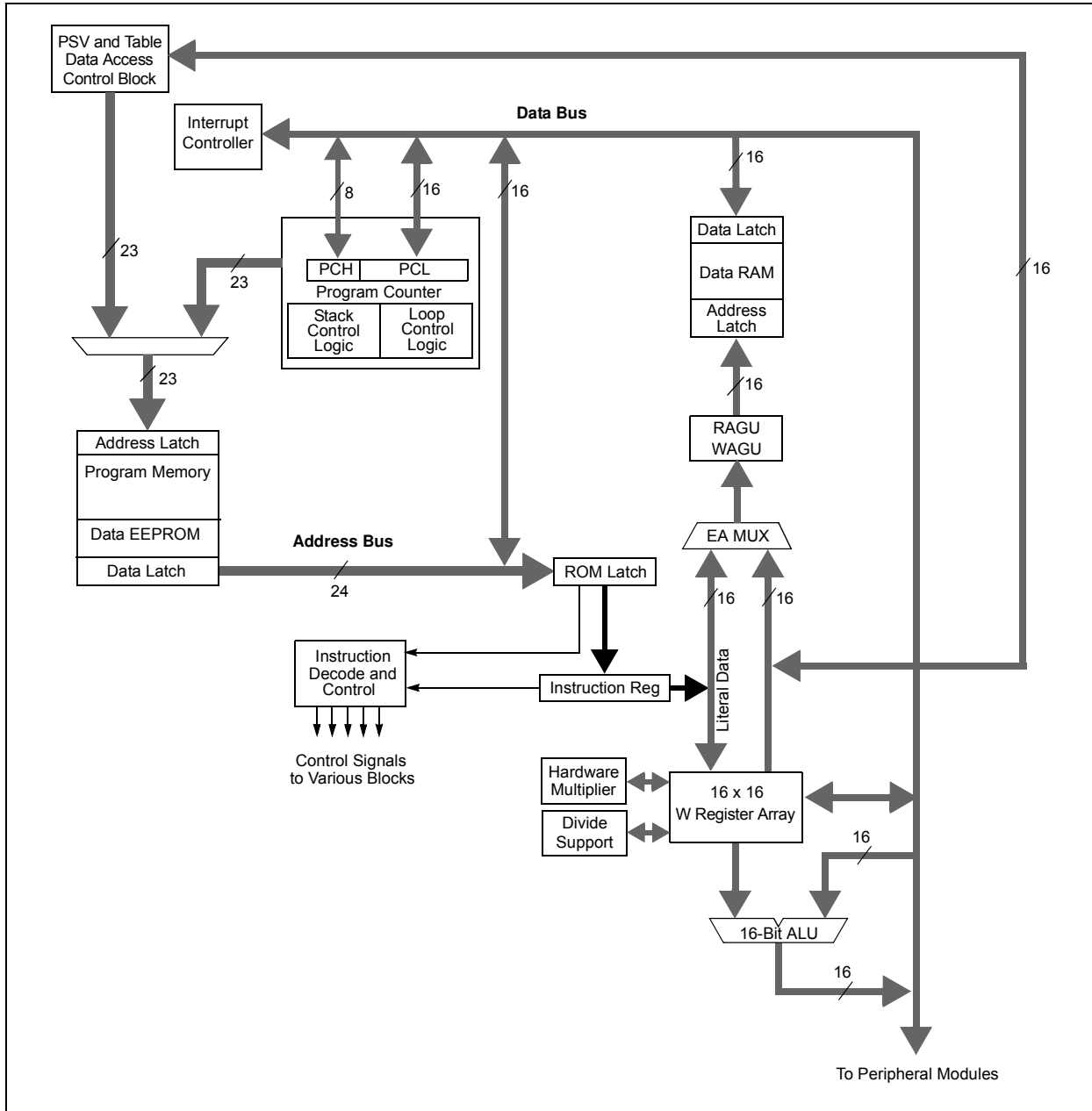
[Figure 3-2](#) displays the programmer's model for the PIC24F. All registers in the programmer's model are memory mapped and can be manipulated directly by instructions.

[Table 3-1](#) provides a description of each register. All registers associated with the programmer's model are memory mapped.



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**FIGURE 3-1: PIC24F CPU CORE BLOCK DIAGRAM**



**TABLE 3-1: CPU CORE REGISTERS**

Register(s) Name	Description
W0 through W15	Working Register Array
PC	23-Bit Program Counter
SR	ALU STATUS Register
SPLIM	Stack Pointer Limit Value Register
TBLPAG	Table Memory Page Address Register
PSVPAG	Program Space Visibility Page Address Register
RCOUNT	Repeat Loop Counter Register
CORCON	CPU Control Register

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**FIGURE 3-2: PROGRAMMER'S MODEL**

